

PATENT

Docket No.: M4065.0018/P018-A

#21 re
LMD
5.5.00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Rodney Langley et al.

Serial No.: Not Yet Assigned

Group Art Unit: Not Yet Assigned

Filed: Concurrently Herewith

Examiner: Not Yet Assigned

For: METHOD AND APPARATUS FOR
PLASMA ETCHING A WAFER

Assistant Commissioner for Patents
Washington, D.C. 20231

FIRST PRELIMINARY AMENDMENT

Dear Sir:

Prior to examination on the merits, please amend the above-identified U.S.
patent application as follows:

In the Specification:

Page 1, line 2, insert --This is a divisional application of U.S. Ser. No.

09/074,591, which was filed on May 8, 1998, --now US Pat. # 6,080,272.

Page 6, line 5, cancel "to provide", substitute --provides--; and

line 18, insert --of-- after "view".

Page 7, line 6, cancel "plate 14", substitute --assembly 14--; and

MA
8/6/02